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Vishay Semiconductors

AUTOMOTIVE

COMPLIANT HALOGEN

FREE

# Hyperfast Rectifier, 2 A FRED Pt®

### eSMP® Series



**Top View** 

**Bottom View** 

### SlimSMAW (DO-221AD)



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS					
I <sub>F(AV)</sub>	2 A				
$V_{R}$	100 V, 200 V				
V <sub>F</sub> at I <sub>F</sub>	0.69 V				
I <sub>FSM</sub>	60 A				
t <sub>rr</sub> (typ.)	15 ns				
T <sub>J</sub> max.	175 °C				
Package	SlimSMAW (DO-221AD)				
Circuit configuration	Single				

#### **FEATURES**

- Low profile package
- · Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, class 2 whisker test
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### **DESCRIPTION / APPLICATIONS**

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial, and automotive applications.

### **MECHANICAL DATA**

Case: SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating

Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002

Polarity: color band denotes cathode end

ABSOLUTE MAXIMUM RATINGS						
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Peak repetitive reverse	VS-2EYH01HM3	V		100	V	
voltage	VS-2EYH02HM3	$V_{RRM}$		200	<b>V</b>	
Average rectified forward current		I <sub>F(AV)</sub> (1)	T <sub>C</sub> = 151 °C	2	Α	
Non-repetitive peak surge current		I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 10 ms sine pulse wave	60		
Operating junction and storage temperatures		T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C	

### Note

(1) Mounted on infinite heatsink

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking VS-2EYH01HM3	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	100	-	-	V
voltage VS-2EYH02HM3			200	-	-	
Forward voltage, per diode	V <sub>F</sub>	I <sub>F</sub> = 2 A	-	0.86	0.93	
	VF.	I <sub>F</sub> = 2 A, T <sub>J</sub> = 150 °C	-	0.69	0.75	
Reverse leakage current, per diode	I_	V <sub>R</sub> = V <sub>R</sub> rated	-	-	2	μΑ
neverse leakage current, per diode	I <sub>R</sub>	$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	1	20	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	_	12	-	pF

# VS-2EYH01HM3, VS-2EYH02HM3

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS
	t <sub>rr</sub>	I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt =	$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		22	-	
		$I_F = 1.0 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	15	-	ns
Reverse recovery time		I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1A, I <sub>rr</sub> = 0.25 A		-	-	28	
		T <sub>J</sub> = 25 °C	$I_F = 2 \text{ A},$ $dI_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 100 \text{ V}$	-	16	-	
		T <sub>J</sub> = 125 °C		-	26	-	
Peak recovery current		T <sub>J</sub> = 25 °C		-	2.7	-	۸
	I <sub>RRM</sub>	M T <sub>J</sub> = 125 °C		-	3.4	-	A
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	20	-	200
		T <sub>J</sub> = 125 °C		-	43	-	nC

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		-55	-	175	°C
Thermal resistance, junction to mount		R <sub>thJM</sub> (1)	Infinite heatsink	-	12	15	
Thermal resistance, junction to ambient		R <sub>thJA</sub>	Device mounted on FR4 PCB, 2 oz. standard footprint	-	120	150	°C/W
VS-2EYH01HM3			Case style SlimSMAW (DO-221AD)		2H1		
Marking device	VS-2EYH02HM3		Case style Sill ISWAW (DO-22 IAD)	2H2			

#### Note

<sup>(1)</sup> Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

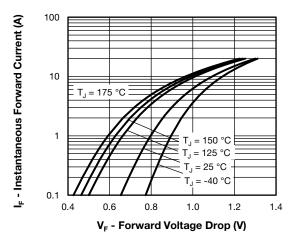


Fig. 1 - Typical Forward Voltage Drop Characteristics

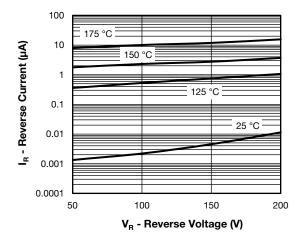


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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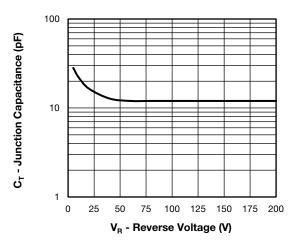


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

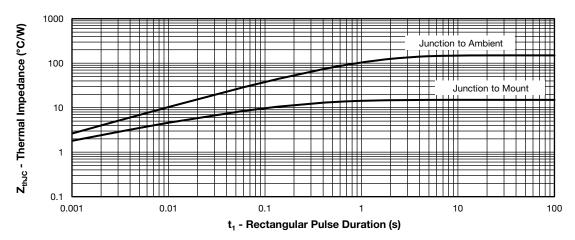


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

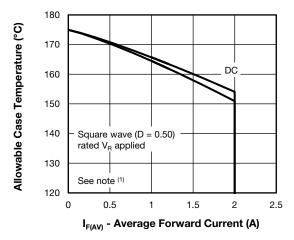


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

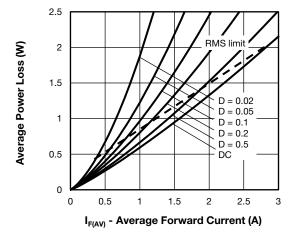


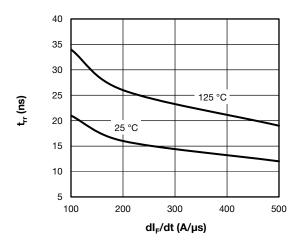
Fig. 6 - Forward Power Loss Characteristics

### Note

Formula used: T<sub>C</sub> = T<sub>J</sub> - (Pd + Pd<sub>REV</sub>) x R<sub>th,JC</sub>; Pd = forward power loss = I<sub>F(AV)</sub> x V<sub>FM</sub> at (I<sub>F(AV)</sub>/D) (see fig. 5); Pd<sub>REV</sub> = inverse power loss = V<sub>R1</sub> x I<sub>R</sub> (1 - D); I<sub>R</sub> at V<sub>R1</sub> = rated V<sub>R</sub>

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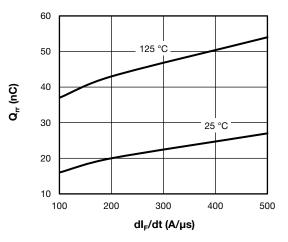
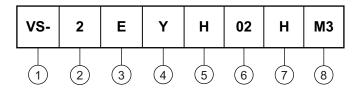


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Current rating (2 = 2 A)

3 - Circuit configuration:

E = single diode

Y = SlimSMAW (DO-221AD)

**5** - Process type,

H = hyperfast recovery

Voltage code (02 = 200 V)

7 - H = AEC-Q101 qualified

8 - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	PACKAGING DESCRIPTION			
VS-2EYH01HM3/H	0.033	Н	3500	7"diameter plastic tape and reel			
VS-2EYH01HM3/I	0.033	1	14 000	13"diameter plastic tape and reel			
VS-2EYH02HM3/H	0.033	Н	3500	7"diameter plastic tape and reel			
VS-2EYH02HM3/I	0.033	1	14 000	13"diameter plastic tape and reel			

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?96582</u>					
Part marking information	www.vishay.com/doc?95562				
Packaging information	www.vishay.com/doc?88869				
SPICE model	www.vishay.com/doc?96585				

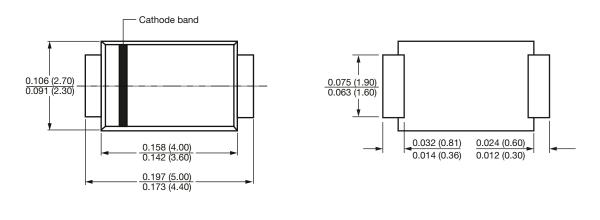


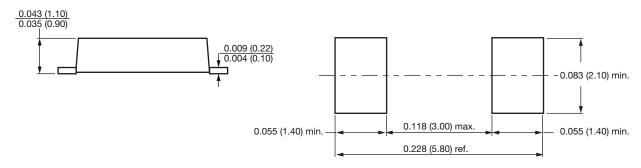
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# SlimSMAW (DO-221AD)

## **DIMENSIONS** in inches (millimeters)

## SlimSMAW (DO-221AD)





Mounting pad layout



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